

Nch 40V 80A Power MOSFET

V _{DSS}	40V
R _{DS(on)} (Max.)	4.7mΩ
I _D	±80A
P_D	78W

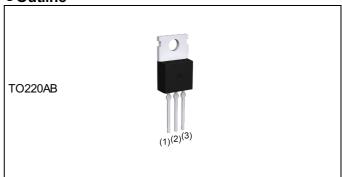
Features

- 1) Low on resistance
- 2) High power small mold package (TO220AB)
- 3) Pb-free lead plating; RoHS compliant
- 4) 100% UIS tested

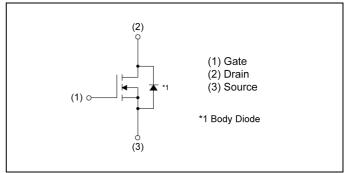
Application

Switching

Outline



•Inner circuit



Packaging specifications

	Packing	Tube
Turno	Basic ordering unit (pcs)	500
Type	Taping code	C10
	Marking	RX1G08CGN

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V _{DSS}	40	V
Continuous drain current	V _{GS} = 10V	I _D *1	±80	А
Pulsed drain current	l _{DP} *2	±160	А	
Gate - Source voltage	V _{GSS}	±20	V	
Avalanche current, single pulse	I _{AS} *3	30	А	
Avalanche energy, single pulse	E _{AS} *3	35	mJ	
Power dissipation	P _D *1	78	W	
Junction temperature	T _j	150	°C	
Operating junction and storage tem	T _{stg}	-55 to +150	°C	

●Thermal resistance

Parameter	Symbol	Values			Lleit
Faranieter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC} *1	-	1	1.6	°C/W

● Electrical characteristics (T_a = 25°C)

Daramatar	Cymahal	Conditions	Values			l limit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		40	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_i} I_D = 1 \text{mA}$ referenced to 25°C		-	26.2	-	mV/°C	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 40V, V _{GS} = 0V	-	-	1	μA	
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±500	nA	
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 0.5$ mA	1.0	-	2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I _D = 1mA referenced to 25°C	-	-4.9	-	mV/°C	
Static drain - source	D *4	V _{GS} = 10V, I _D = 80A	-	3.5	4.7	0	
on - state resistance	R _{DS(on)} *4	V _{GS} = 4.5V, I _D = 40A	-	4.4	5.9	mΩ	
Gate resistance	R _G f = 1MHz, open drain		-	3.4	-	Ω	
Forward Transfer Admittance	Y _{fs} *4	V _{DS} = 5V, I _D = 40A	35	-	-	S	

^{*1} Tc=25°C, Limited only by maximum temperature allowed.

^{*2} Pw \leq 10 μ s , Duty cycle \leq 1%

^{*3} L \simeq 0.05mH, V_{DD} = 20V, R_G = 25 Ω , Starting T_j = 25 $^{\circ}$ C Fig.3-1,3-2

^{*4} Pulsed

● Electrical characteristics (T_a = 25°C)

Darameter	Symbol	Conditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C _{iss}	V _{GS} = 0V	-	2410	-	
Output capacitance	C _{oss}	V _{DS} = 20V	-	370	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	135	-	
Turn - on delay time	t _{d(on)} *4	V _{DD} ≈ 20V,V _{GS} = 10V	1	17	1	
Rise time	t _r *4	I _D = 40A	1	9	ı	no
Turn - off delay time	t _{d(off)} *4	$R_L \simeq 0.5\Omega$		70		ns
Fall time	t _f *4	$R_G = 10\Omega$	-	16	-	

• Gate charge characteristics $(T_a = 25^{\circ}C)$

Daramatar	Cymahal	Conditions		Values			1.1:4		
Parameter	Symbol Conditions		IONS	Min.	Тур.	Max.	Unit		
T. I. I. I. I. O. *4	O *4		V _{GS} = 10V	-	32	-			
Total gate charge	Q _g *4	Q_g .	Q_g	V _{DD} ≈ 20V		-	15.8	-	
Gate - Source charge	Q _{gs} *4	I _D = 40A	V _{GS} = 4.5V	-	6.0	-	nC		
Gate - Drain charge	Q _{gd} *4				-	4.5	-		

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions		Unit		
raiametei	eter Symbol (Min.	Тур.	Max.	Offic
Continuous forward current	I _S	T _a = 25°C	1	-	65	Α
Pulse forward current	I _{SP} *2	1 _a - 25 C	-	-	160	Α
Forward voltage	V _{SD} *4	$V_{GS} = 0V, I_{S} = 65A$	-	-	1.2	V
Reverse recovery time	t _{rr} *4	I _S = 50A, V _{GS} =0V	-	34	-	ns
Reverse recovery charge	Q _{rr} *4	di/dt = 100A/μs	1	32	1	nC

Fig.1 Power Dissipation Derating Curve

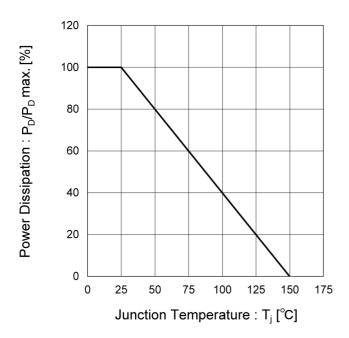
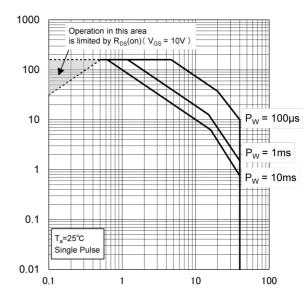


Fig.2 Maximum Safe Operating Area



Drain Current : I_D [A]

Drain - Source Voltage: V_{DS}[V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

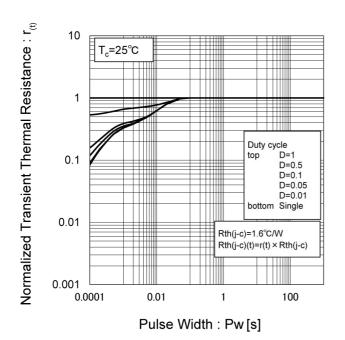
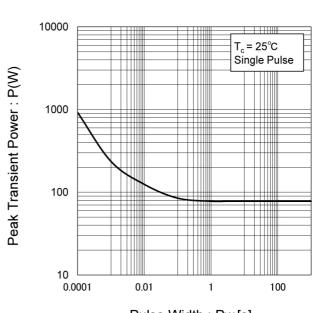


Fig.4 Single Pulse Maximum Power dissipation



Pulse Width: Pw[s]

Fig.5 Typical Output Characteristics(I)

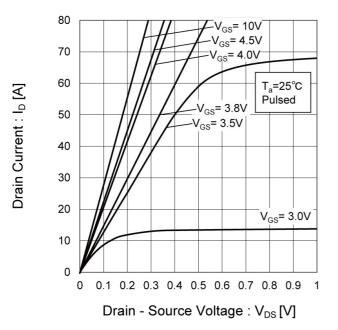
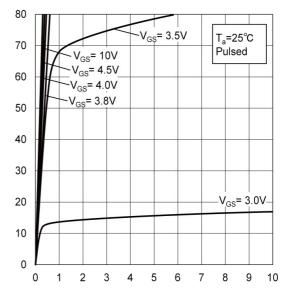


Fig.6 Typical Output Characteristics(II)

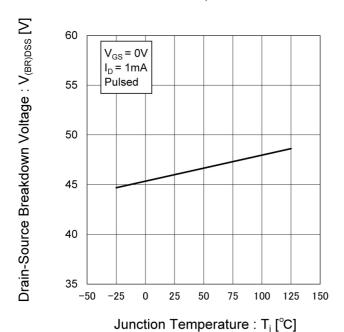


Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.7 Breakdown Voltage vs.

Junction Temperature



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Fig.8 Typical Transfer Characteristics

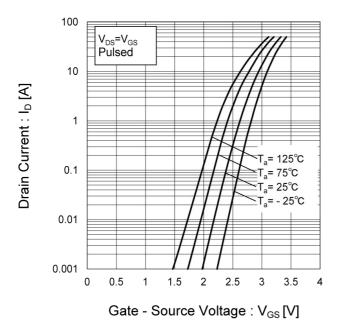


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

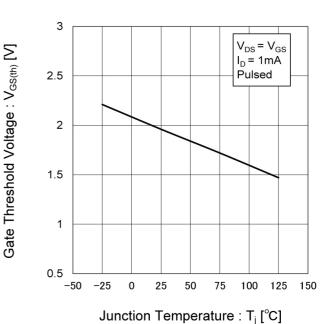


Fig.10 Forward Transfer Admittance vs.
Drain Current

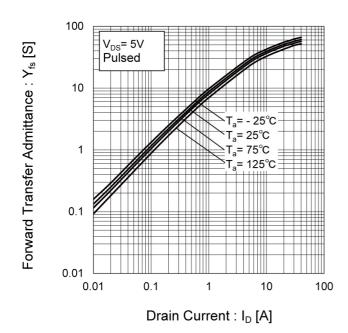


Fig.11 Drain Current Derating Curve

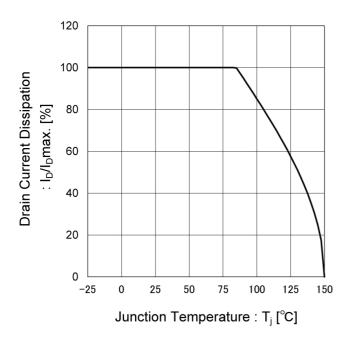
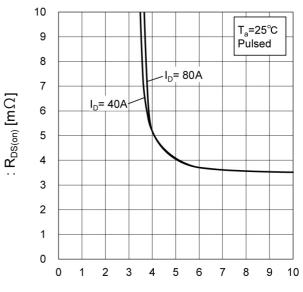
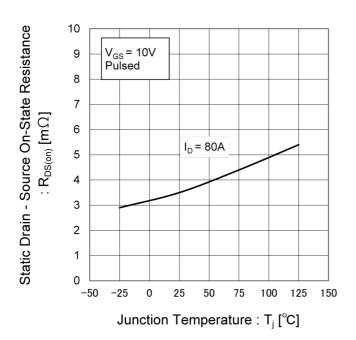


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



Gate - Source Voltage : $V_{GS}[V]$

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



Static Drain - Source On-State Resistance

Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

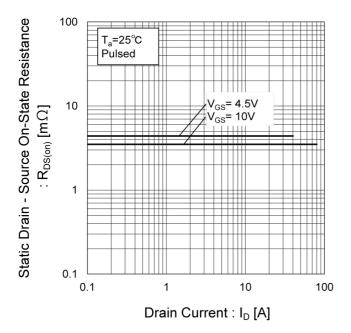


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

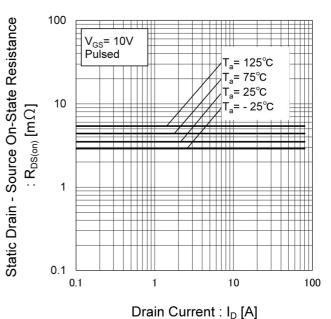


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

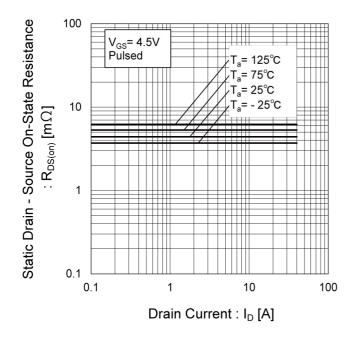


Fig.17 Typical Capacitance vs.

Drain - Source Voltage

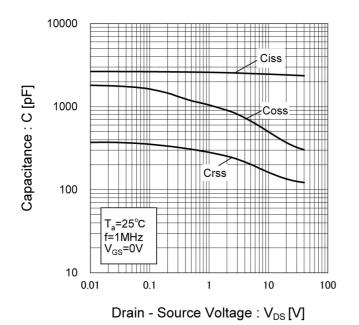


Fig.18 Switching Characteristics

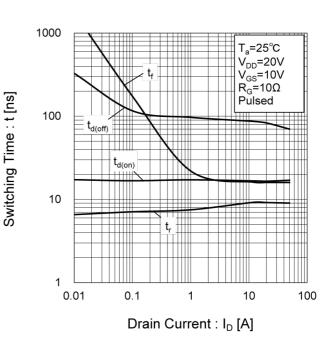


Fig.19 Dynamic Input Characteristics

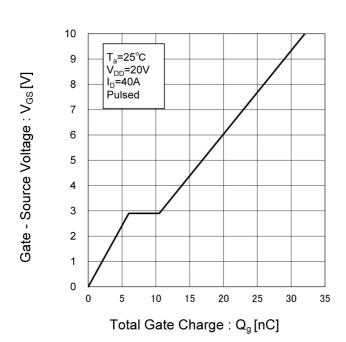
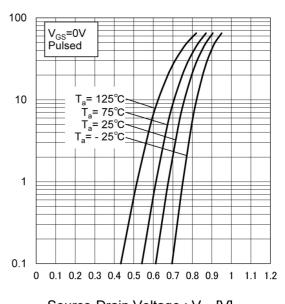


Fig.20 Source Current vs.

Source Drain Voltage



Source Current : Is [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

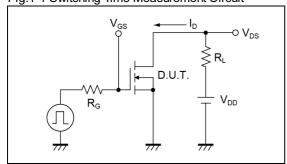


Fig.2-1 Gate Charge Measurement Circuit

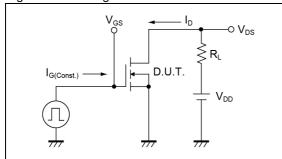


Fig.3-1 Avalanche Measurement Circuit

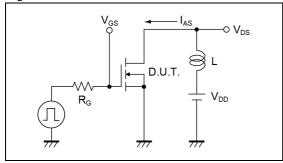


Fig.1-2 Switching Waveforms

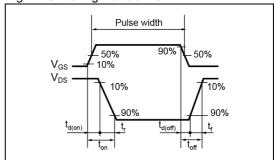


Fig.2-2 Gate Charge Waveform

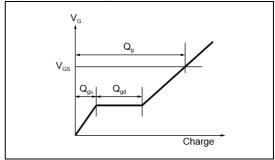
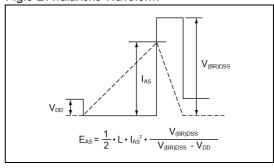
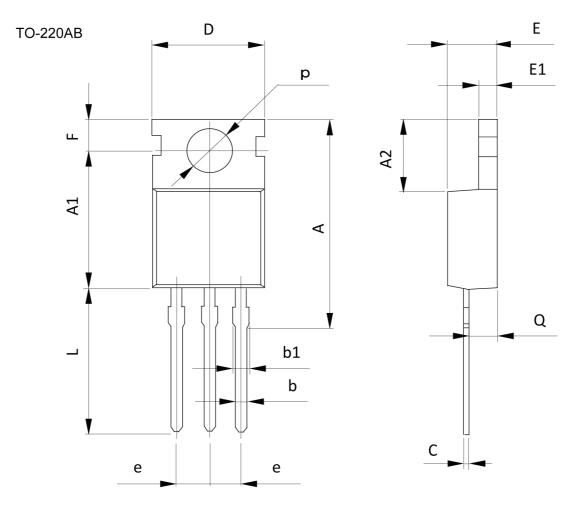


Fig.3-2 Avalanche Waveform



Dimensions



DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	18.3	18.95	0.720	0.746
A1	12.7	13.1	0.500	0.516
A2	6.3	6.7	0.248	0.264
b	0.6	1	0.024	0.039
b1	1.07	1.47	0.042	0.058
С	0.4	0.7	0.016	0.028
D	9.7	10.1	0.382	0.398
E	4.3	4.7	0.169	0.185
е	2.5	54	0.1	00
E1	1.1	1.5	0.043	0.059
F	2.6	3.2	0.102	0.126
L	9.88	10.28	0.389	0.405
р	3.4	3.8	0.134	0.150
Q	2.2	2.6	0.087	0.102

Dimension in mm/inches

Notice

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JAPAN	USA	EU	CHINA
CLASSⅢ	CI ACCIII	CLASS II b	CI VCCIII
CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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RX1G08CGN - Web Page

Part Number	RX1G08CGN
Package	TO220AB
Unit Quantity	1000
Minimum Package Quantity	50
Packing Type	Tube
Constitution Materials List	inquiry
RoHS	Yes